

DERWENT-ACC-NO: 1994-005312

DERWENT-WEEK: 199401

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TITLE: Evaporation type cooling of
semiconductor devices used
on traction unit and power supply
substations - has pipes
of condenser bent in form of frames
and forming channels
for liq in vol. of evaporator

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PATENT-ASSIGNEE: LENG D RAIL ENG INST[LERE]

PRIORITY-DATA: 1991SU-4951931 (May 4, 1991)

PATENT-FAMILY:

PUB-NO	PAGES	PUB-DATE	MAIN-IPC
SU 1781735 A1		December 15, 1992	N/A
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APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
SU 1781735A1	N/A	
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INT-CL (IPC): H01L023/427, H01L025/00

ABSTRACTED-PUB-NO: SU 1781735A

BASIC-ABSTRACT:

The heat dissipation cycle from the semiconductor device
(2) to an ambient air
is continuously carried out during a current load. If a
tubular condenser (4)
has several pipes in the form of frames, hence the boiling
and condensation
processes a liq intermediate heat carrier is performed

parallel for each frame.
The heat dissipated in the semiconductor device (2) is transferred to evaporator (1) designed as a packet of pipes.

USE/ADVANTAGE - In power electronics, for cooling of semiconductor devices of traction substation of underground trains, rectifier plants of electric and diesel locomotives. Improved efficiency and reliability of operation.
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CHOSEN-DRAWING: Dwg.1/4

DERWENT-CLASS: U11 V04

EPI-CODES: U11-D02D; V04-T03;

